



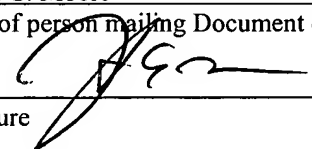
IFW

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

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Amendment, Commissioner for Patents, P.O. Box 1450,
Alexandria, VA 22313-1450 on February 28, 2005
(Date of Deposit)

Harold C. Moore

Name of person mailing Document or Fee


Signature

February 28, 2005

Date of Signature

Re:	Application of:	Tilke et al.
	Serial No.:	10/780,276
	Filed:	February 17, 2004
	For:	Semiconductor Structure with Increased Breakdown Voltage and Method for Producing the Semiconductor Structure
	Group Art Unit:	2811
	Examiner:	Thien F. Tran
	Our Docket No.:	1890-0061

TRANSMITTAL

Please find for filing in connection with the above patent application the
following:

1. Response to Restriction Requirement; and
2. One (1) return post card.

* The fee has been calculated as shown below.

CLAIMS AS AMENDED				
	Claims Remaining After Amendment	Highest No. Paid For	Fee Calculation	Addit Fee
Total Claims	16	20	0 X 18	\$ 0.00
Independent Claims	2	3	0 X 84	\$ 0.00
Total Additional Fee Required				\$ 0.00

Please charge any fee deficiency, or credit any overpayment, to Deposit Account No. 13-0014; but not to include any payment of issue fees.

Respectfully Submitted,

MAGINOT, MOORE & BECK



February 28, 2005

Harold C. Moore
Registration No. 37,892
Bank One Center/Tower
111 Monument Circle, Suite 3000
Indianapolis, Indiana 46204-5115

Enclosures



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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	Group Art Unit:	2811
	Confirmation No.:	7063
	Examiner:	Thien F. Tran
	Our Docket No.:	1890-0061

RESPONSE TO OFFICE ACTION

Sir:

In response to the Office Action dated January 27, 2005 for the above-identified patent application, please amend the application as follows:

Amendments to the claims begin on page 2 of the paper.